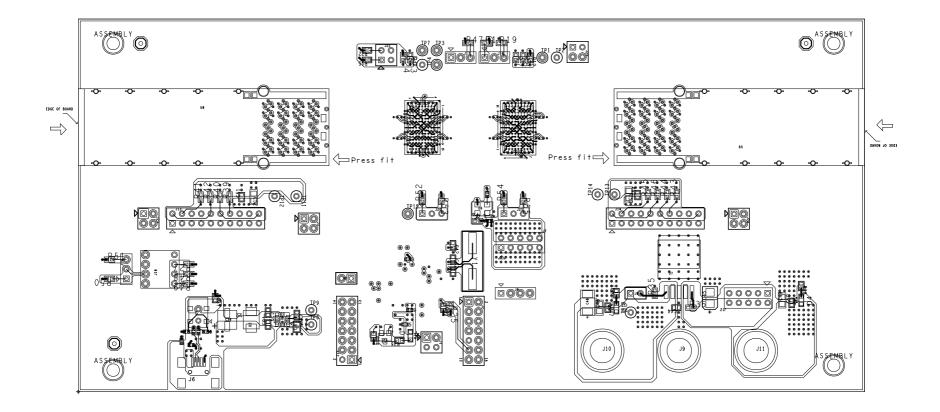
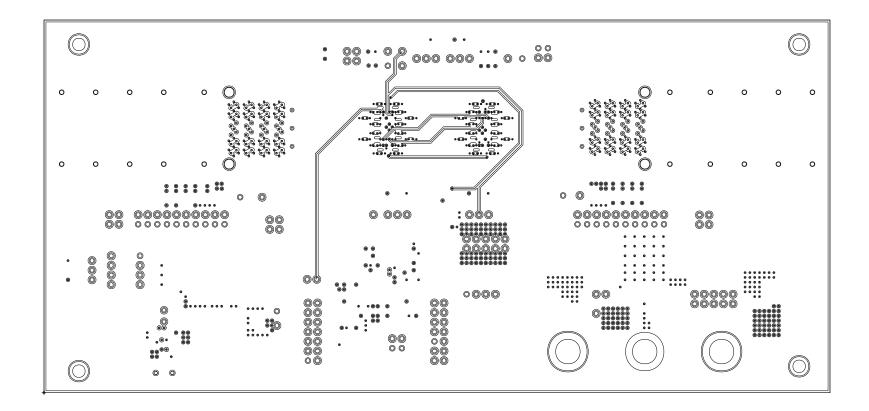
ART FILM - 01-TOP



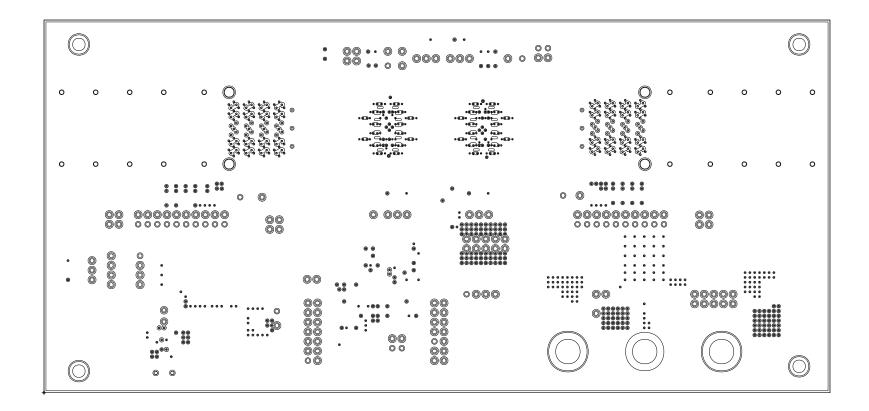
Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV:A
DATE: June 2015 JOB: SV601171		REV:A
LAYER: DS2808R810_QSFP_0609_PCB #B#W888YTCP		

ART FILM - 02-ART-1



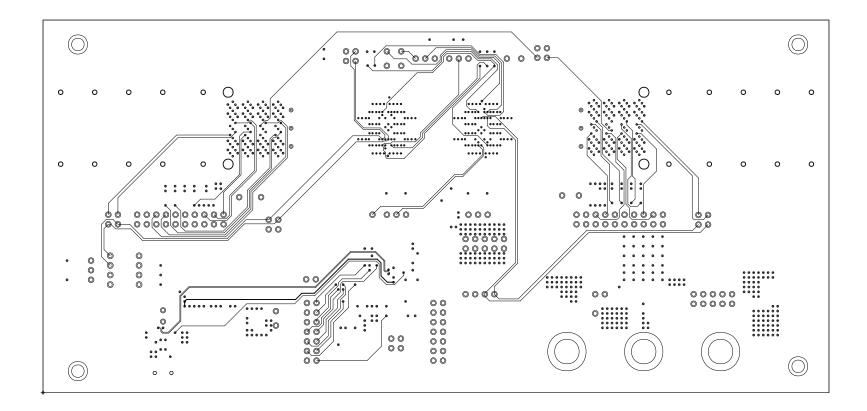
Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB ARTWORK LAYER02		

ART FILM - 03-GND-1



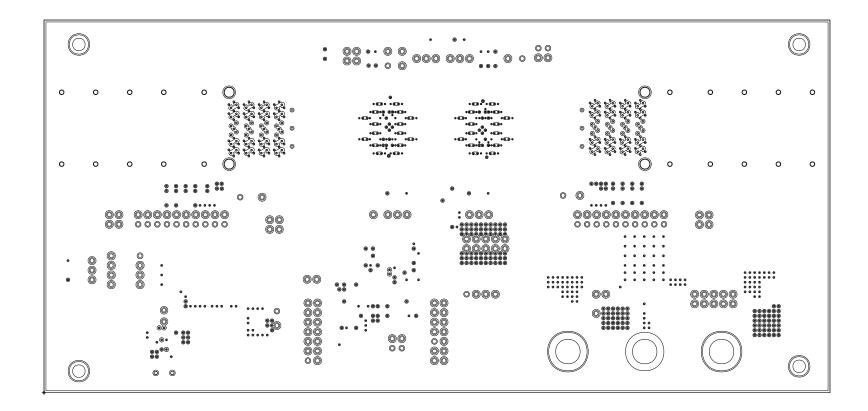
Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB GROUND PLANE03		

ART FILM - 04-ART-2



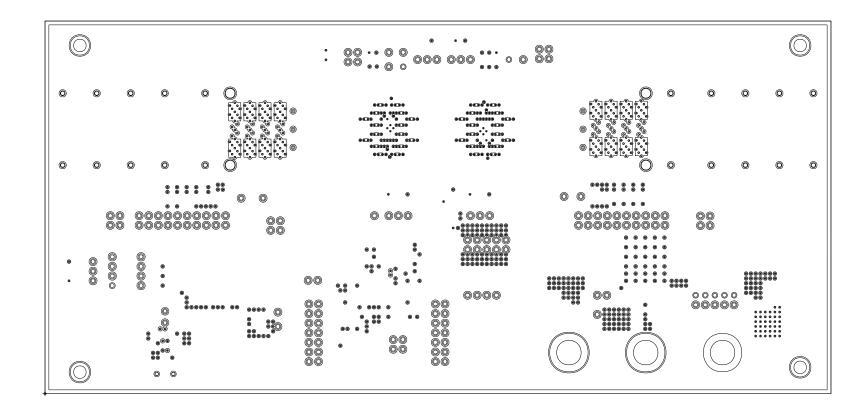
Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB ARTWORK LAYER04		

ART FILM - 05-GND-2



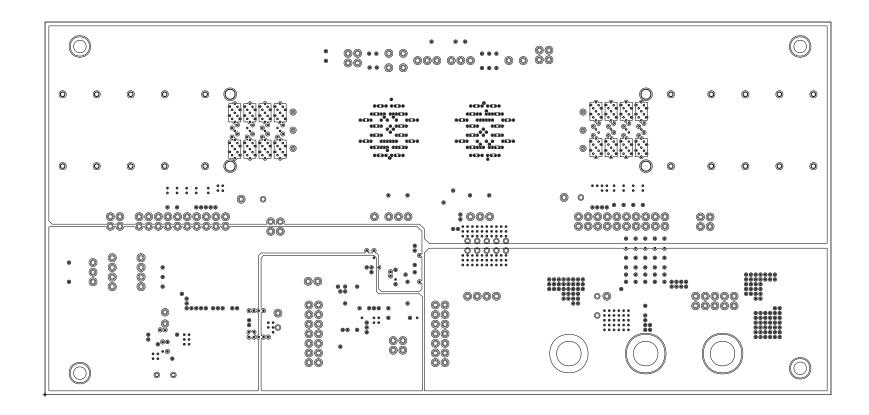
Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015	JOB: SV601171	REV:A
LAYER: DS280BR810_OSFP_0609_PCB GROUND PLANE05		

ART FILM - 06-VDD-1



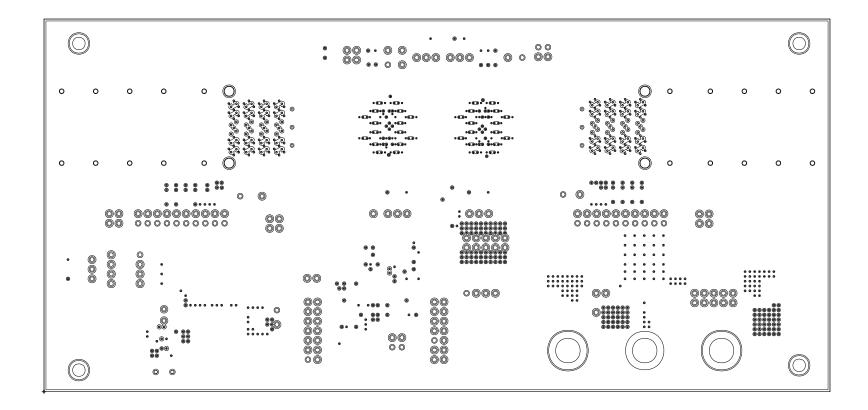
Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB POWER PLANE06		

ART FILM - 07-VDD-2

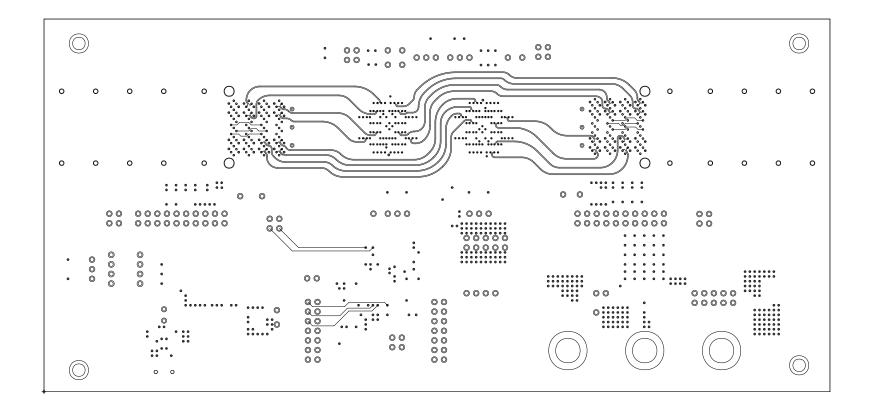


Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV:A
LAYER: DS280BR810_QSFP_0609_PCB POWER PLANE07		

ART FILM - 08-GND-3

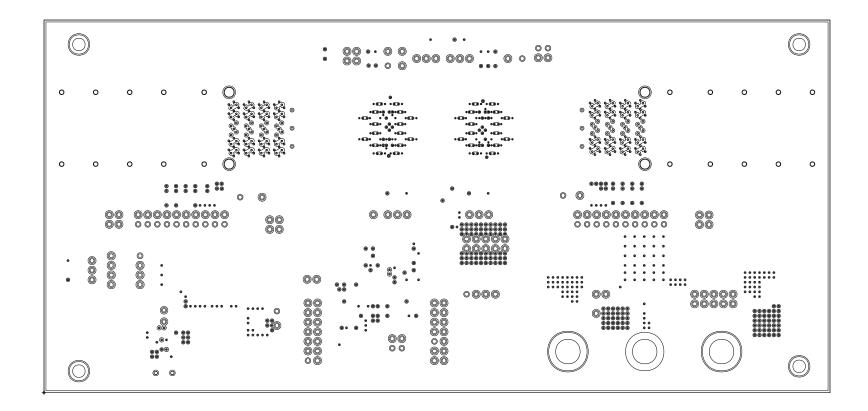


Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV:A
LAYER: DS280BR810_QSFP_0609_PCB GROUND PLANE08		

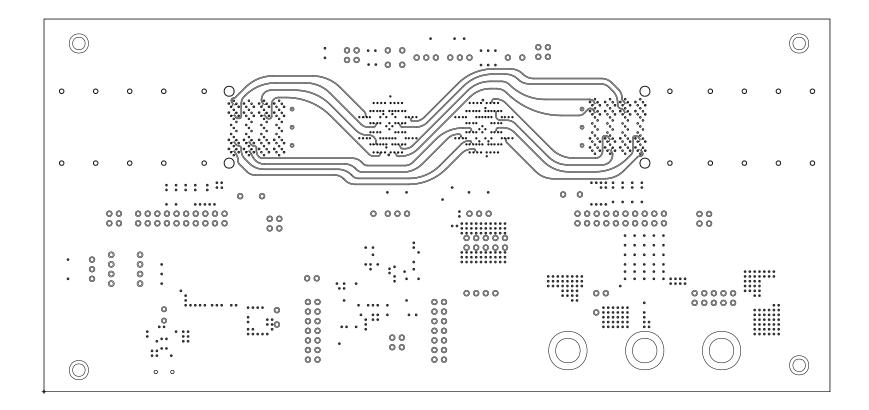


TEXAS INSTRUMENTS		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV : A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB ARTWORK LAYER09		

ART FILM - 10-GND-4

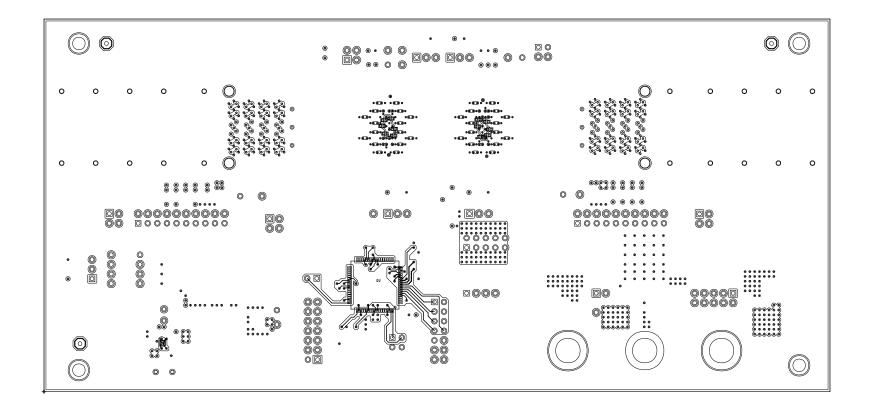


TEXAS INSTRUME	NTS	
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DATE: June 2015	JOB: SV601171	REV: A
LAYER: DS280BR810_QSFP_0609_PCB GROUND PLANE10		



Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB ARTWORK LAYER11		

ART FILM - 12-BOTTOM



Texas Instruments		
NAME: TIDA00427_DS280BR810_OSFP_Reference_Design		REV: A
DATE: June 2015 JOB: SV601171		REV: A
LAYER: DS280BR810_QSFP_0609_PCB BOTWORKABOYTOM		

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